

# **Specification Sheet**

P/N: MCM-0905S-102Y-H-RU

Products: Certifications:

Molded Power Chokes ISO9001

Multilayer Chip Inductors IATF16949

<u>Lan Transformer</u> ISO14001

RF Passive / Antennas QC080000

**Automotive** 

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### **REVISIONS**

REV.	Description	Date	Approvaled by	Checked by	Checked by	Prepared by
00	Issue	2018.03.19	Vincent	Marco	Sara	Stanley

### I.SCOPE:

This specification applies to the Pb Free high current type SMD Common mode filter for MCM-0905S-102Y-H-□□

#### PRODUCT INDENTIFICATION

MCM - 0905S - 102 Y - H - □□-RU

(1)

2

34

(5)

- ① Product Code
- **② Dimensions Code**
- **3 Impedance Code**
- 4 Tolerance
- **(5) Inner Control Code**

### $\Pi$ . INDEX:

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Unless otherwise specified, test condition should be Temp. =  $20\pm5$ °C,

Humidity=35~85%

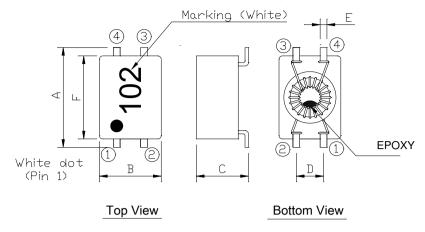
But if needed, then test condition should be Temp.=20±2℃,

Humidity=65±5%

8.SHELF LIFE

Storage Condition:The temperature should be within-40°C ~105°C and humidity should be less than 75%RH. The product should be used within 12 months from the time of delivery. In addition, suggest to use product within 6 months from the time of delivery.

# (1) SHAPES AND DIMENSIONS(mm)



A: 8.90 ±0.50 B: 5.40 ±0.30 C: 5.00 Max. D: 2.54 ±0.30 E: 0.50 Typ. F: 7.30 ±0.30

# (2) ELECTRICAL SPECIFICATIONS **SEE TABLE 1**

**TEST INSTRUMENTS** 

L : HP 4284A PRECISION LCR METER (or equivalent)

RDC: CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)

I.R : CHROMA MODEL 19073 AC/DC/IR HIPOT TESTER (or equivalent)

# (3) CHARACTERISTICS

(3)-1 Operate temperature range .....  $-40^{\circ}$ C  $\sim +125^{\circ}$ C (Including self temp. rise)

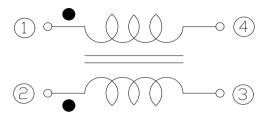
(3)-2 Storage temperature range .....  $-40^{\circ}$ C  $\sim +125^{\circ}$ C

### **TABLE 1**

MAGLAYERS PT/NO.	L(1-4),(2-3) (uH) @100KHz/0.25V	Resistance RDC (Ω) Max. (1 line)	Rated Current (A) Max.	Insulation Resistance (ΜΩ) Min.	Rated Voltage (V) Max.	Marking
MCM-0905S-102Y-H-□□-RU	1000±50%	0.15	1.2	100	80	● <sub>102</sub>

Rated Current : Based on temperature rise ( $\triangle T : 40\%$  Typ.)

### **CIRCUIT DIAGRAM**



# (4) RELIABILITY TEST METHOD

### **MECHANICAL**

TEST ITEM	SPECIFICATION	TEST DETAILS	
Solder ability	The product shall be connected to the test	Apply cream solder to the printed circuit board .	
	circuit board by the fillet (the height is 0.2mm).	Refer to clause 8 for Reflow profile.	
Resistance to	There shall be no damage or problems.	Temperature profile of reflow soldering	
Soldering heat		© 300− soldering (Peak temperature 260±3°C 10 sec)	
(reflow soldering)		e (Feak temperature 26025 € 10 sec.)	
		(Peak temperature 260±3°C 10 sec)  250  English 250  Pre-heating  Pre-heating  Slow cooling  (Stored at room temperature)	
		Pre-heating (230+0°C)	
		Slow cooling (Stored at room	
		1 1/ 1   1	
		50 —/	
		2 min sec. 2 min. or more	
		The specimen shall be passed through the reflow oven	
		with the condition shown in the above profile for 1 time.	
		The specimen shall be stored at standard atmospheric	
		eric conditions for 1 hour, after which the measurement	
		shall be made.	
Terminal strength	The terminal electrode and the ferrite must	Solder a chip to test substrate , and then laterally apply	
	not damaged.	a load 9.8N in the arrow direction.	
		Printed circuit board  \$\phi = \frac{\phi}{\phi} \\ \phi =	
Strength on PC board	The terminal electrode and the ferrite must	Solder a chip to test substrate and then apply a load.	
bending	not damaged.		
		Test board:FR4 100×40×1mm	
		R10 R11 speed:1mm/sec.	
		***	
		45 45 Dimensions in mm	
High	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit	
temperature	Insulation resistance and DC resistance on the	board,the test shall be done.	
resistance	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.	
	The terminal electrode and the ferrite must not	Temperature : +125±2℃	
	damaged.	Applied voltage : Rated voltage	
		Applied current : Rated current	
		Testing time : 500±12 hours	



# (4) RELIABILITY TEST METHOD

### **MECHANICAL**

TEST ITEM	SPECIFICATION	TEST DETAILS
Humidity	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit
resistance	Insulation resistance and DC resistance on the	board,the test shall be done.
	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.
	The terminal electrode and the ferrite must not	Temperature : +60±2℃ , Humidity : 90 to 95 %RH
	damaged.	Applied voltage : Rated voltage
		Applied current : Rated current
		Testing time : 500±12 hours
Thermal shock	Impedance:Within±20% of the initial value. Insulation resistance and DC resistance on the specification(refer to clause 2-1) shall be met. The terminal electrode and the ferrite must not damaged.	1 cycle +125°C 30 min. -40°C 30 min. Testing Time:100 cycle
Low	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test
temperature	Insulation resistance and DC resistance on the	circuit board,the test shall be done.
storage	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.
	The terminal electrode and the ferrite must	Temperature : -40±2℃
	not damaged.	Testing time : 500±12 hours
Vibration	Impedance:Within±20% of the initial value. Insulation resistance and DC resistance on the specification(refer to clause 2-1) shall be met. The terminal electrode and the ferrite must not damaged.	After the samples shall be soldered onto the test circuit board, the test shall be done.  Frequency: 10 to 55 Hz  Amplitude: 1.52 mm  Dimension and times: X,Y and Z directions for 2 hours each.
Solderability	New solder More than 75%	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated over the whole of the sample before hard, the sample shall then be preheated for about 2 minutes in a temperature of 130~150°C and after it has been immersed to a depth 0.5mm below for 3±0.2 seconds fully in molten solder M705 with a temperature of 245±2°C. More than 75% of the electrode sections shall be couered with new solder smoothly when the sample is taken out of the solder bath.

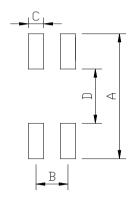


# (5) LAND DIMENSION (Ref.)

PCB: GLASS EPOXY t=1.6mm

### (5)-1 LAND PATTERN DIMENSIONS(mm)

(STANDARD PATTERN)

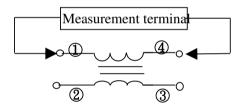


A: 10.50 B: 2.54 C: 1.20 D: 4.50

# (6) TEST EQUIPMENT

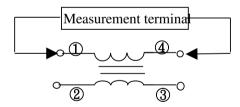
#### (6)-1 Inductance

Measured by using HP4284A



#### (6)-2 DC Resistance

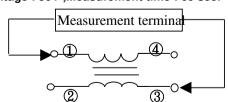
Measured by using Chroma 16502 milliohm meter.



#### (6)-3 Insulation Resistance

Measured by using Chroma 19073

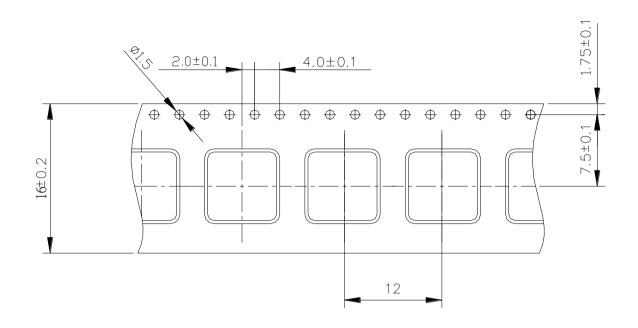
Measurement voltage: 50V, Measurement time: 60 sec.



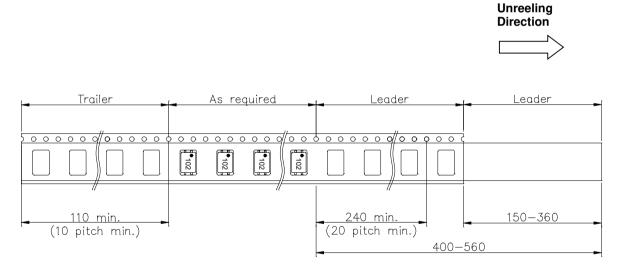


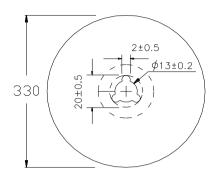
# (6) PACKAGING

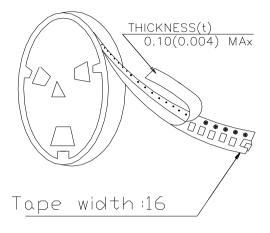
# (6)-1 CARRIER TAPE DIMENSIONS (mm)



# (6)-2 TAPING DIMENSIONS (mm)







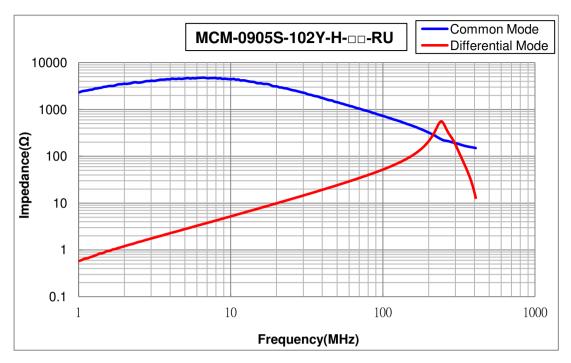
### (b)-4 QUANIII Y

1000 pcs/Reel

The products are packaged so that no damage will be sustained.

# TYPICAL ELECTRICAL CHARACTERISTICS

# Impedance VS. Frequency



# **Temperature VS. DC Current**

